

# Letters

## Gate-Drive Power Supply With Decayed Negative Voltage to Solve Crosstalk Problem of GaN Synchronous Buck Converter

Yu Chen , Member, IEEE, Ruwen Wang, Xinmin Liu , and Yong Kang

**Abstract**—Gallium-Nitride (GaN) transistor suits for high switching frequency condition to build high power density converters. However, it suffers from crosstalk problem especially in bridge-structure applications, that is, the fast voltage changing of the switching node causes a positive or negative voltage spike on the gate-source voltage of GaN transistor, which results in false turn-ON and gate breakdown of the transistor, respectively. Rather than specially designing the gate driver, this letter proposes an idea of using a gate-drive power supply (GDPS) with decayed negative output to solve the crosstalk problem. With the proposed GDPS, a negative driving voltage is provided when the positive voltage spike appears to avoid false turn-ON, and then the negative driving voltage naturally decays to zero before the negative voltage spike appears to avoid gate breakdown. Such a GDPS is realized by a simple forward-flyback topology, and the commercial gate-drive ICs can be cooperated with it conveniently. Experimental results show the effectiveness of the proposed method.

**Index Terms**—Crosstalk, forward-flyback, Gallium-Nitride (GaN) transistor, gate-drive power supply (GDPS), synchronous buck converter.

### I. INTRODUCTION

NOWADAYS, power electronic converters are moving toward high power density. In order to improve power density of converters, the switching frequency should be increased to reduce the volume of passive components. Wide-bandgap devices, such as Gallium-Nitride (GaN) transistor, suit for this scenario. Compared with Si devices such as Si MOSFET, GaN transistor has much lower gate charge  $Q_g$ , zero gate-drain recovery charge  $Q_{rr}$ , and lower ON-state resistance  $R_{ds(on)}$ , so it can switch faster with less switching and conduction losses [1], [2].

However, GaN transistor has higher switching speed, lower threshold voltage, and lower minimum allowable gate-source

voltage, and thus it is severely affected by the crosstalk problem especially in bridge-structure applications. When a GaN transistor switches, a rapid voltage change of the switching node is caused, and an unwanted positive voltage spike or negative voltage spike appears on the gate-source voltage of its complementary switch [3], [4]. The positive voltage spike may exceed the threshold voltage  $V_{th}$ , causing false turn-ON. Therefore, a bipolar gate-drive power supply (GDPS) is usually needed to provide a negative driving voltage, reducing the potential of the positive voltage spike to avoid false turn-ON. However, when the negative voltage spike appears, the superposition of the negative voltage spike and the negative voltage may exceed the minimum allowable gate-source voltage of GaN transistor, resulting in gate breakdown [5].

To solve the contradiction above, many driving circuits have been presented. A complete driving circuit includes a gate driver and a GDPS, and the researchers usually focus on the gate driver design, considering the GDPS as a standard device. One kind of method is to reduce the switching speed of the switch which causes crosstalk. Increasing the turn-ON/turn-OFF gate-resistance and paralleling an external gate-source capacitor can decrease the switching speed; however, it increases the switching loss. Another kind of method is to enhance the noise-immune ability of the switch suffering from crosstalk. Paralleling an external gate-source capacitor can decrease the amplitude of voltage spikes while it brings in additional switching losses [4], [5]. Adding auxiliary circuit or changing gate-resistance can offer a low impedance path and thus can decrease both of the positive and negative voltage spikes [6]–[10]. Multilevel gate driver can also be utilized to increase the safe driving voltage margin [11]–[13]. For example, Zhang *et al.* [11] and Zhang *et al.* [12] used a full bridge structure to introduce multilevel driving voltage, and He *et al.* [13] used a voltage divider to split the voltage of the GDPS into a positive voltage and a negative voltage, and then used an extra switch to discharge the negative voltage capacitor. However, the methods above need to specially design the gate driver, and it is more likely to introduce stray parameters between the driven switch and the GDPS because the gate drivers are more complicated.

Noticing that the output voltage of the gate driver can also be controlled by its GDPS, we therefore propose to solve the crosstalk problem by designing the GDPS. Different from the existing power supplies with regulated and constant

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Yu Chen, Ruwen Wang, Xinmin Liu, and Yong Kang are with the State Key Laboratory of Advanced Electromagnetic Engineering and Technology, Hubei 430074, China, and also with the School of Electrical and Electronic Engineering, Huazhong University of Science and Technology, Hubei 430074, China (e-mail: ayu03@163.com; rwwang@hust.edu.cn; lxmhust@hust.edu.cn; ykang@hust.edu.cn).

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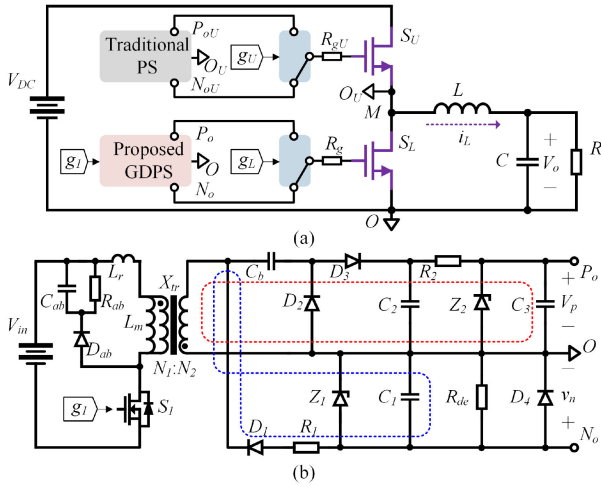


Fig. 1. Topologies of (a) synchronous buck converter and (b) proposed GDPS.

multioutputs [1], [14]–[17], a negative voltage is generated by the proposed GDPS when the positive voltage spike appears to avoid false turn-ON, and then the negative voltage naturally decays to zero before the negative voltage spike appears to avoid gate breakdown. The contributions of this letter are as follows.

- 1) Rather than designing the gate driver [6]–[13], the proposed method solves the crosstalk problem through designing the GDPS. The commercial gate-drive ICs can be utilized, and hence the complexity and stray parameters resulted from the gate driver can be avoided.
- 2) Rather than obtaining the multilevel voltage by extra active switches [11]–[13], the proposed GDPS provides a decayed negative voltage. By cooperating with the commercial gate-drive ICs, the multilevel driving voltage can be obtained and it is always under the right potential when the positive and negative crosstalk occur.
- 3) Compared with the existing multioutput forward or fly-back converters [1], [14]–[17], the proposed GDPS is simpler since it fully uses the nature of forward-flyback and voltage doubler structures, and thus, only one active switch and one winding are required.

The rest of this letter is organized as follows. In Section II, the proposed GDPS is introduced and a synchronous buck converter with the proposed GDPS is analyzed. In Section III, the experimental prototype is built to verify the validity. Finally, the conclusion is given in Section IV.

## II. PROPOSED GDPS

### A. Topology Description

Fig. 1(a) shows a synchronous buck converter.  $S_U$  is the control switch;  $S_L$  is the synchronous switch;  $L$  is the inductor; and  $C$  is the output capacitor. The drivers of  $S_U$  and  $S_L$  are supplied by a traditional PS (power supply) and the proposed GDPS, respectively. Fig. 1(b) shows the topology of the proposed GDPS. It contains one transformer  $X_{tr}$  (with turn ratio  $N = N_1:N_2$ , where  $N_1$  and  $N_2$  are the winding turns of the primary side and secondary side, respectively), and one switch

$S_1$  on the primary side. With capacitor  $C_b$ , diodes  $D_2$  and  $D_3$ , a voltage doubler circuit is structured and two independent loops, i.e., the positive loop (the red path) and the negative loop (the blue path), are formed to generate the positive constant voltage  $V_p$  and the decayed negative voltage  $v_n$ , respectively. The gating signal  $g_1$  of  $S_1$  is cooperated with  $g_U$  (the gating signal of  $S_U$ ).  $C_2$ ,  $C_3$ , and  $C_b$  are relatively large ( $\mu\text{F}$  magnitude) to keep  $V_p$  constant.  $C_1$  is relatively small (several nF) to ensure the fast-generating and rapid-decay of  $v_n$ . Resistor  $R_2$  and Zener diode  $Z_2$  are used to fine-tune  $V_p$ , and resistor  $R_1$  and Zener diode  $Z_1$  are used to fine-tune  $v_n$ . In addition,  $C_{ab}$ ,  $R_{ab}$ , and  $D_{ab}$  form a snubber to absorb the energy stored in leakage inductor  $L_r$ .  $D_4$  is used to clamp  $v_n$ , and  $R_{dc}$  is used to accelerate the decay.

### B. Operation Modes

Fig. 2 shows the operation modes. The fine-tuning circuit ( $R_2$  and  $Z_2$ ) are merged as the load of  $V_p$  and the snubber is ignored for simplification. Fig. 3 shows the key waveforms. Besides, only the continuous current mode (CCM) of the synchronous buck converter is considered in this letter and the direction of the inductor current,  $i_L$ , stays the same. Before Mode I,  $S_U$  is OFF and  $S_L$  is ON;  $i_L$  flows through  $S_L$ . The voltage of  $C_1$  is stabilized at  $V_{n0}$ .

*Mode I* [ $t_0, t_1$ ]: At  $t_0$ , the gate signal  $g_L = 0$  and point  $G$  connects to point  $N$ . The turning-OFF loop (including gate-source capacitor  $C_{gsL}$ , gating resistor  $R_g$ , parasitic inductor  $L_g$ , the gate-drive IC, and  $C_1$ , see the green line) is formed. Since  $C_1$  is small, it is discharged quickly and  $v_n$  decays to zero from negative value rapidly. However, since  $S_1$  is still in ON-state ( $g_1 = 1$ ),  $C_1$  gets energy supplement from the PS  $V_{in}$  through the negative loop (see the blue line) and  $v_n$  can be recovered to  $V_{n1}$  at  $t_1$ . At the same time, the loop including the secondary winding,  $D_2$  and  $C_b$  is formed (see the red line), and  $C_b$  is charged for later boost purpose.

For the synchronous buck converter, although  $S_L$  is in OFF-state,  $i_L$  can still flow through  $S_L$  in the reverse direction.

*Mode II* [ $t_1, t_2$ ]: At  $t_1$ , the gate signal  $g_1 = 0$  so  $S_1$  is turned OFF. The energy stored in the magnetic inductance  $L_m$  of transformer  $X_{tr}$  transfers to  $C_2$  through the positive loop (see the red line). Since  $C_b$  is in series in the loop,  $V_p$  is boosted to a high level to adapt the requirement of turning-ON. At the same time, since no energy can be sent to  $C_1$  through the negative loop, the negative output  $v_n$  decays naturally from  $V_{n1}$  to zero.

In addition, at  $t_1$ , the gate signal  $g_U = 1$  and  $S_U$  is turned ON.  $v_M$  (the voltage potential of node  $M$ ) steps from zero rapidly with high  $dv/dt$ , causing charging current of the gate-drain capacitor  $C_{gdL}$  and the drain-source capacitor  $C_{dsL}$  of  $S_L$ . Part of the charging current flows through the turning-OFF loop (see the green line), resulting in a positive voltage spike  $v_{sp+}$  on  $R_g$  and  $L_g$ . However, since  $v_n$  is now the negative  $V_{n1}$ , the gate-source voltage  $v_{gsL} = V_{n1} + v_{sp+}$  is always below  $V_{th}$ . After  $t_1$ ,  $v_n$  decays to zero. Since no more positive voltage spike will appear, such a zero gate-source voltage is safe.

For the synchronous buck converter,  $S_U$  is always ON after  $t_1$  so  $i_L$  flows through it in this mode. Since  $S_L$  is always OFF in

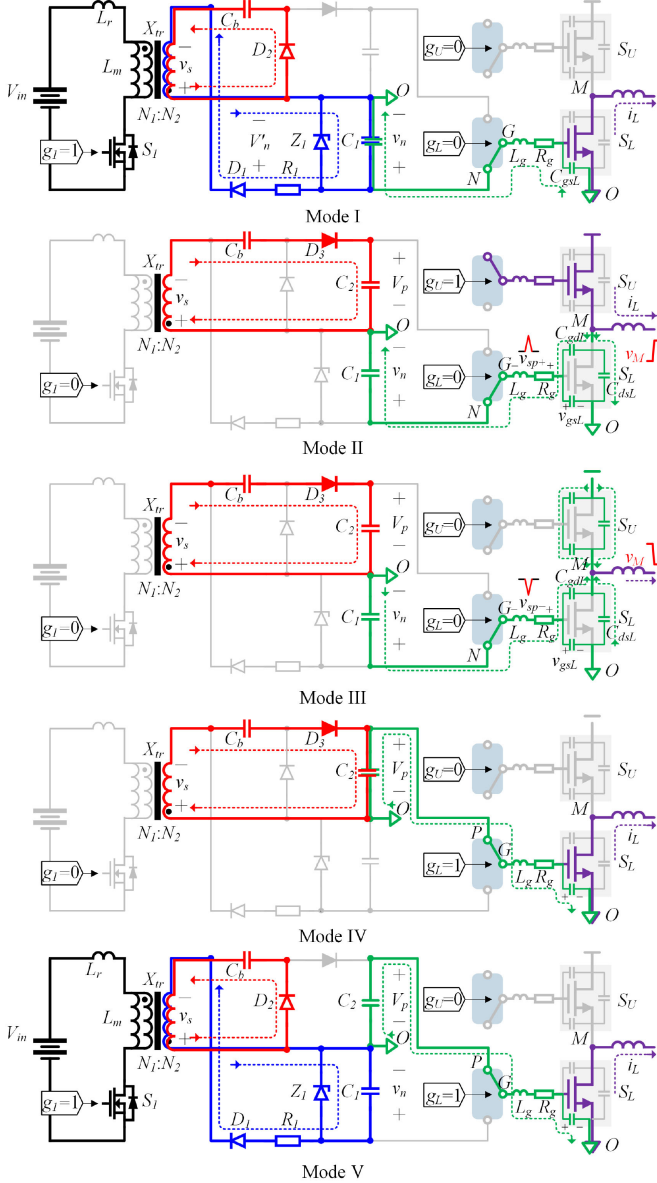


Fig. 2. Equivalent circuits of operation modes.

this mode, the delay of  $g_1$  and the turn-OFF performance of  $S_1$  will not affect the operation of the synchronous buck converter.

**Mode III** [ $t_2, t_3$ ]: At  $t_2$ , the gate signal  $g_U = 0$  and  $S_U$  of the synchronous buck converter is turned OFF.  $i_L$  charges the parasitic capacitors of  $S_U$  and discharges  $C_{dsL}$  and  $C_{gdL}$  of  $S_L$ . The discharging current flowing through  $C_{gdL}$  and the turning-OFF loop causes a negative voltage spike  $v_{sp-}$  on  $R_g$  and  $L_g$  (see the green line). Since  $v_n$  has decayed to zero before  $t_2$ ,  $v_{gsL} = 0 + v_{sp-}$  (where  $v_{sp-}$  is negative value) can be far away from the minimum allowable gate-source voltage, protecting the transistor from gate breakdown.

**Mode IV** [ $t_3, t_4$ ]: At  $t_3$ ,  $C_{dsL}$  is fully discharged to zero, and the gate signal  $g_L = 1$  can be applied (the point  $G$  turns to point  $P$ ). The turning-ON loop (including gate-source capacitor  $C_{gsL}$ , gating resistor  $R_g$ , parasitic inductor  $L_g$ , the gate-drive

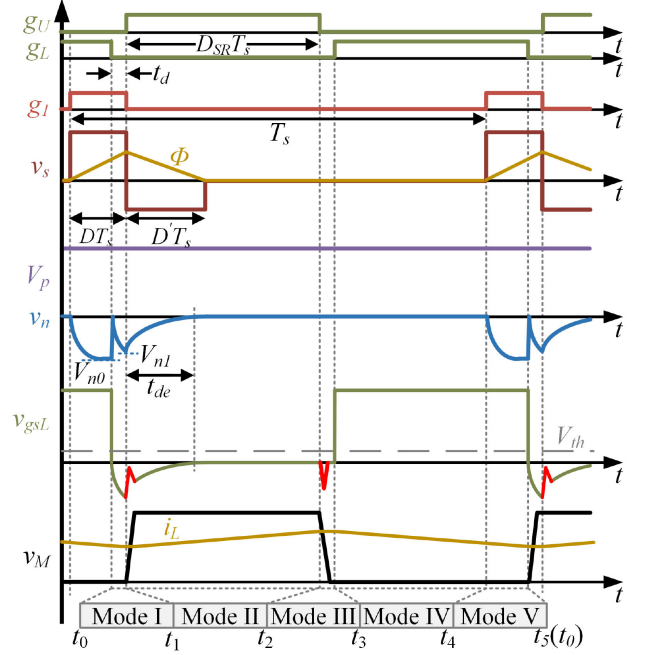


Fig. 3. Key waveforms of the proposed GDPS and the synchronous buck converter.

IC, and  $C_2$ , see the green line) is formed and gets energy from  $C_2$ . Therefore,  $S_L$  is turned ON and  $i_L$  flows through it to achieve synchronous rectification. Since  $v_M$  is almost unchanged, no voltage spike appears on the gate-source voltage of  $S_U$ .

Besides, the energy stored in  $L_m$  might be run out during mode II, mode III, or mode IV. After that, the positive loop (see the red line) is cut off and no energy is sent to  $C_2$ . However, stable  $V_p$  can still be guaranteed since the capacitance of  $C_2$  is large.

**Mode V** [ $t_4, t_5$ ]: At  $t_4$ , the gate signal  $g_1 = 1$  and  $S_1$  is turned ON.  $C_1$  is charged again through the negative loop (see the blue line). Since  $C_1$  is relatively small, it is charged rapidly and then  $v_n$  is stable at  $V_{n0}$ , preparing the initial voltage for the next cycle. At the same time,  $C_b$  is charged through the secondary side of  $X_{tr}$  and  $D_2$  (see the red line).

Since  $S_L$  is always on in this mode, the delay of  $g_1$  and the turn-ON performance of  $S_1$  will not affect the operation of the synchronous buck converter.

### C. Parameter Design

During mode I and mode V,  $S_1$  is in ON-state. Since the ON-resistance of  $S_1$  is small, it is ignored during analysis. The increment of  $\Phi$  can be expressed as

$$\Delta\Phi_+ = (V_{Cb} + V_D)DT_s/N_2 \quad (1)$$

where  $D$  is the duty cycle of  $g_1$ ;  $T_s$  is the period of proposed GDPS;  $V_D$  is the forward voltage of diode  $D_2$ ; and  $V_{Cb}$  is the voltage of  $C_b$ .  $V_{Cb}$  is constant since  $C_b$  is relatively large and can be expressed as

$$V_{Cb} = V_{in}L_m/[N(L_m + L_r)] - V_D. \quad (2)$$

During modes II, III, and IV,  $S_1$  is in OFF-state and the decrement of  $\Phi$  can be expressed as

$$\Delta\Phi_- = (V_p - V_{Cb} + V_D)D'T_s/N_2 \quad (3)$$

where  $D'$  is the duty cycle that energy transfers to the positive loop. Since  $\Delta\Phi_+ = \Delta\Phi_-$ ,  $D'$  can be derived as

$$D' = D(V_D + V_{Cb})/(V_D + V_p - V_{Cb}). \quad (4)$$

To achieve the working condition in Fig. 3, i.e.,  $\Phi$  decreases to zero before  $t_4$ ,  $D' < 1 - D$  needs to be met.

$P_p$ , the dissipative power of  $V_p$ , can be expressed as  $V_p I_p$ , where  $I_p$  is the average dissipative current and should be equal to the average current flowing into  $C_2$ . Therefore

$$P_p = V_p I_p = V_p I_{smax} D' / 2 \quad (5)$$

where  $I_{smax}$  is the maximum current of the secondary side, and  $I_{smax} = N I_{pmax} = N [V_{in} D T_s / (L_m + L_r)]$ . With (2), (4), and (5),  $V_p$  can be derived as

$$V_p = \frac{2P_p(L_m + L_r)(L_m V_{in} - 2L_m N V_D - 2L_r N V_D)}{2P_p N L_m^2 + 2N P_p L_r^2 + 4N P_p L_m L_r - N D^2 V_{in}^2 T_s L_m}. \quad (6)$$

Thus, to generate the desired  $V_p$ , the corresponding duty cycle  $D$  can be derived from (6) as

$$D = \sqrt{\frac{2P_p(L_m + L_r)[N(L_m + L_r)(2V_D + V_p) - L_m V_{in}]}{L_m N T_s V_{in}^2 V_p}}. \quad (7)$$

Meanwhile  $V'_n$ , the voltage of negative loop before fine-tuning (see the blue line in mode I of Fig. 2), can be expressed as  $-V_{Cb}$ . In addition, to get the desired  $V_{n1}$  through fine-tuning by  $R_1$  and  $Z_1$ ,  $V'_n \geq V_{n1}$  should be met.

Besides, the decay time  $t_{de}$  can be calculated as

$$t_{de} = 3R_{neq}(C_1 + C_{gsL}) \quad (8)$$

where  $R_{neq}$  is the equivalent resistor of the negative loop and  $t_{de}$  can be shortened through paralleling an energy releasing resistance  $R_{de}$  with  $C_1$ , which is equivalent to decreasing  $R_{neq}$ .

Furthermore,  $D_{SR}$ , the duty cycle of the synchronous buck converter, should satisfy  $t_{de}/T_s < D_{SR} < 1 - D$ . Otherwise,  $v_n$  would still be negative when  $S_U$  is turned OFF, as the counterexamples shown in Fig. 4. In such cases, the negative voltage spike resulted from the turn-OFF process would be superposed on the negative  $v_n$ , increasing the risk of gate breakdown.

### III. EXPERIMENTAL VERIFICATION

#### A. Parameters and Design Considerations

To verify the effectiveness of the proposed GDPS, a prototype is built, as shown in Fig. 5(a) and (b). The key parameters of the proposed GDPS and the synchronous buck converter are listed in Table I, and the control signals  $g_U$ ,  $g_L$ ,  $g_1$  are all generated by DSP TMS320F28377S. The switching frequency is 500 kHz. The minimal switching transient of GaN transistor is about 5.4 ns, which results in serious crosstalk problem to the synchronous switch  $S_L$ . Therefore, the proposed GDPS is used to supply the gate driver of  $S_L$  in the prototype.

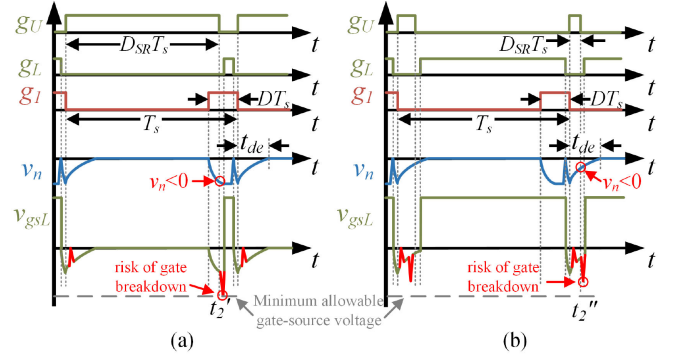


Fig. 4. Key waveforms (a) when the restriction  $D_{SR} < 1 - D$  is not satisfied and (b) when the restriction  $t_{de}/T_s < D_{SR}$  is not satisfied.

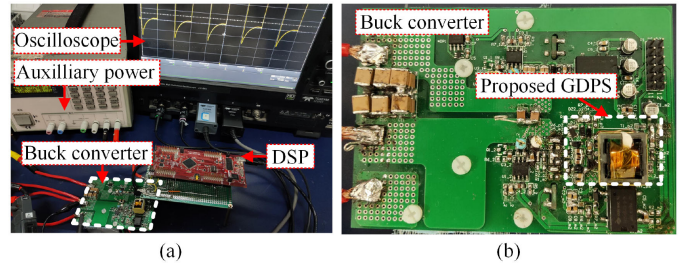


Fig. 5. Photographs of (a) prototype and (b) details of the synchronous buck converter.

TABLE I  
PARAMETERS OF THE PROPOSED GDPS AND THE SYNCHRONOUS BUCK CONVERTER

Parameter	Value	Parameter	Value
$S_U$ and $S_L$	GS66508T	Driver IC	Si8271
$S_1$	SQ2348ES	$V_{DC}$	300V
$V_0$	130V	$T_s/f_s$	2 $\mu$ s/500kHz
$D_{SR}$	0.45	$R_{gon}$	12 $\Omega$
$R_{goff}$	2 $\Omega$	$L$	176 $\mu$ H
$t_d$	60ns	$V_{in}$	5V
$L_m$	20 $\mu$ H	$L_r$	3 $\mu$ H
$N$	1	$V_D$	0.32V
$D$	0.16	$C_1$	2.2nF
$C_2$	30 $\mu$ F	$C_3$	30 $\mu$ F

Since the switching speed of GaN transistor is fast, the switching speed of  $S_1$  should be comparable so that it can cooperate better with the GaN transistor. Fortunately, the operation voltage of the GDPS is low, and thus low-voltage Si MOSFET can meet the requirement above. SQ2348ES, a low-voltage Si MOSFET, is chosen as  $S_1$  in our design. The rise time and fall time given in the datasheet are 8 and 6 ns, respectively, which approach to the switching performance of the GaN transistor. In addition, since the gate charge and ON-resistance of  $S_1$  are about 8 nC and 0.032  $\Omega$ , respectively, and the operating current of the proposed GDPS is very small, the calculated switching loss is as low as 20 mW.

According to the analysis in modes II and V, the switching performance of  $S_1$  will not affect the operation of the synchronous buck converter. However,  $C_1$  should adapt to the deadtime since it is recharged during the deadtime period. With the parameters of the experimental prototype,  $C_1 = 2.2$  nF is chosen so that

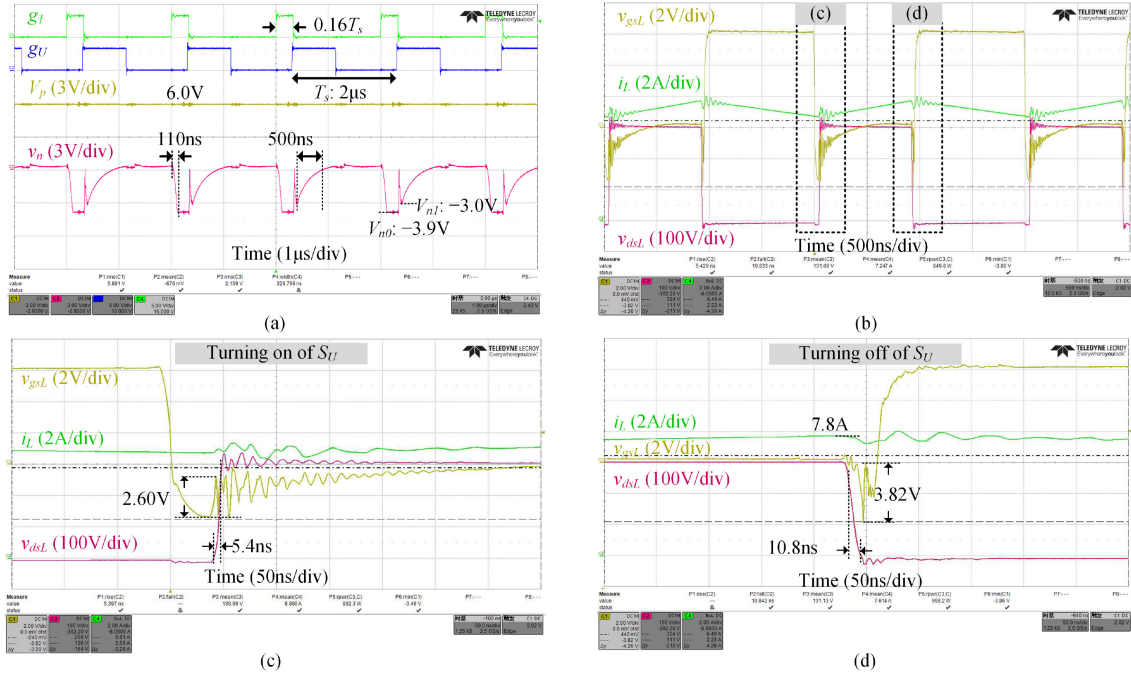


Fig. 6. Waveforms of (a) control signals and the proposed GDPS and (b) synchronous buck converter; the detailed waveforms of (c) turning ON of  $S_U$  and (d) turning OFF of  $S_U$ .

$v_n$  can reach the desired value  $V_{n1}$ .  $D$  is set as 0.16 to get the desired  $V_p = 6.2$  V;  $V'_n$  can be calculated as  $-4.03$  V, so that  $Z_1$  can fine-tune the negative voltage  $v_n$ ;  $t_{de}$  is chosen as 500 ns, so,  $R_{de} = 200 \Omega$  is paralleled with  $C_1$ .  $P_p$  can be estimated to be 60 mW. Besides, the restriction for  $D_{SR}$  can be calculated as  $0.25 < D_{SR} < 0.84$ . It implies that the synchronous buck converter can adapt to the wide range change of the input or output voltage in most of the CCM applications.

### B. Experimental Results

The waveforms of the proposed GDPS are shown in Fig. 6(a). It can be seen that  $g_1$  is ahead of  $g_U$ . When  $g_1$  is high,  $v_n$  increases to  $-3.9$  V in 110 ns, and rapidly decays to zero due to the turning-OFF of  $S_L$ . However,  $v_n$  can recover fast since the GDPS still works under forward mode, so  $V_{n0} = -3.0$  V can be obtained when  $S_U$  is turned ON. It is seen that  $v_n$  decays to zero before  $S_U$  is turned OFF with  $t_{de} = 500$  ns. At the same time,  $V_p$  keeps constant at 6.0 V. Above phenomena are consistent with our design.

Fig. 6(b) shows the waveforms of the synchronous buck converter (working under 300 V, 7.25 A), with details in Fig. 6(c) and (d). Fig. 6(c) shows the turning-ON process of  $S_U$ . When  $S_U$  is turned ON,  $v_M$  rises from 0 to 300 V in 5.4 ns ( $dv/dt = 55.6$  V/ns), and a positive voltage spike with the amplitude of 2.60 V appears. However, the negative voltage  $V_{n1} = -3.0$  V has been prepared, so  $v_{gsL}$  is lower than  $-0.40$  V. Since the parasitic inductance exists in the turning-ON loop, a high-frequency oscillation on  $v_{gsL}$  can be observed, however,  $v_{gsL}$  can always be lower than 0 V. Fig. 6(d) shows the turning-OFF process of  $S_U$ . When  $S_U$  is turned OFF,  $i_L = 7.8$  A charges and discharges the parasitic capacitances of  $S_U$  and  $S_L$ , respectively, making  $v_M$  vary from 300 to 0 V within 10.8 ns ( $dv/dt = 27.8$  V/ns). A negative voltage

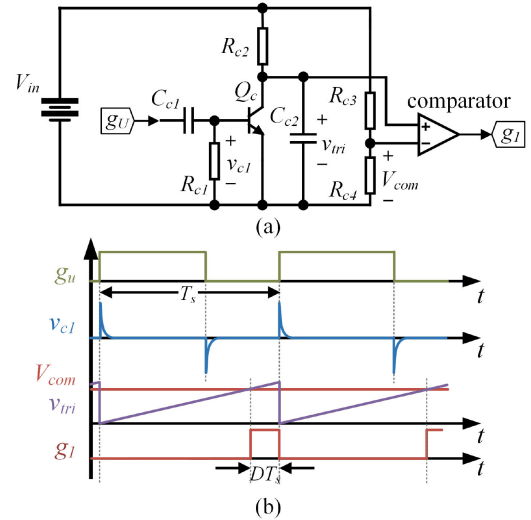


Fig. 7. Simple circuit to generate  $g_1$  according to  $g_U$ . (a) Circuit diagram. (b) Key waveforms.

spike with the amplitude of 3.82 V appears. Since  $v_n$  has already decayed to zero,  $v_{gsL}$  is within the maximum negative voltage limitation with sufficient margin. The above phenomena match well with the analysis, and the GaN transistor has been well protected.

### C. Discussion

In order to provide the right potential of  $v_n$  for the gate driver when the positive voltage spike or the negative voltage spike appears, the frequency of  $g_1$  should be exactly the same as the frequency of the synchronous buck converter. When the working frequency of the synchronous buck converter changes, the

parameters of the proposed GDPS should be fine-tuned according to part C, Section II, and  $g_1$  should also be generated properly. Nevertheless, the generation of  $g_1$  is easy. In our experiment,  $g_1$  is generated conveniently by an ePWM unit in the same DSP that is used to generate  $g_U$  and  $g_L$ . If  $g_U$  and  $g_L$  are generated by the analog methods, the simple circuit shown in Fig. 7(a) can be used to generate  $g_1$  according to  $g_U$ , and the key waveforms are shown in Fig. 7(b). When  $g_U$  is inputted, the high-pass filter ( $C_{c1}$  and  $R_{c1}$ ) outputs a positive pulse  $v_{c1}$  which is aligned with the rising edge of  $g_U$ .  $v_{c1}$  triggers the transistor  $Q_e$  to discharge  $C_{c2}$  rapidly. After discharging,  $V_{in}$  charges  $C_{c2}$  again through  $R_{c2}$ , and  $v_{tri}$ , the voltage across  $C_{c2}$ , increases almost linearly until the next positive pulse  $v_{c1}$  appears. A constant voltage  $V_{com}$  is formed by the voltage divider ( $R_{c3}$  and  $R_{c4}$ ), and therefore,  $g_1$  can be generated through comparing  $v_{tri}$  with  $V_{com}$  by the comparator, and the duty cycle  $D$  can be fine-tuned by  $V_{com}$ .

#### IV. CONCLUSION

To solve the crosstalk problem in GaN synchronous buck converter, this letter proposes a method based on a GDPS with forward-flyback topology. The proposed GDPS can provide a constant positive 6.0-V voltage and a decayed negative output voltage. A  $-3.0$ -V negative driving voltage is provided when the positive voltage spike resulted from crosstalk appears, and the gate-source voltage is lower than 0 V to avoid false turn-ON. This  $-3.0$ -V voltage then decays to 0 V before the negative voltage spike appears to avoid gate breakdown. The loss of the GDPS in our experiments is about 24 mW. The proposed GDPS is low-cost and simple-structured, and can be cooperated with the commercial gate-drive ICs conveniently.

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